





N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| V _{(BR)DSS} | R _{DS(on) max} | I _D Τ _A = +25°C |
|----------------------|--------------------------------|---|
| | 0.4Ω @ $V_{GS} = 4.5V$ | 1.5A |
| 20V | 0.5 Ω @ V _{GS} = 2.5V | 1.3A |
| | 0.7 Ω @ V _{GS} = 1.8V | 1.1A |

Features and Benefits

- Low On-Resistance
- Very Low Gate Threshold Voltage V_{GS(TH)}, 1.0V Max.
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surfaced Mount Package
- Ultra-Low Package Profile, 0.4mm Maximum Package Height
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(on)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- Power Management Functions

Mechanical Data

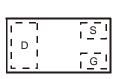
- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208
- Weight: 0.001 grams (Approximate)



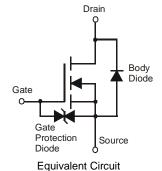




Bottom View



Top View Internal Schematic



Ordering Information (Note 4)

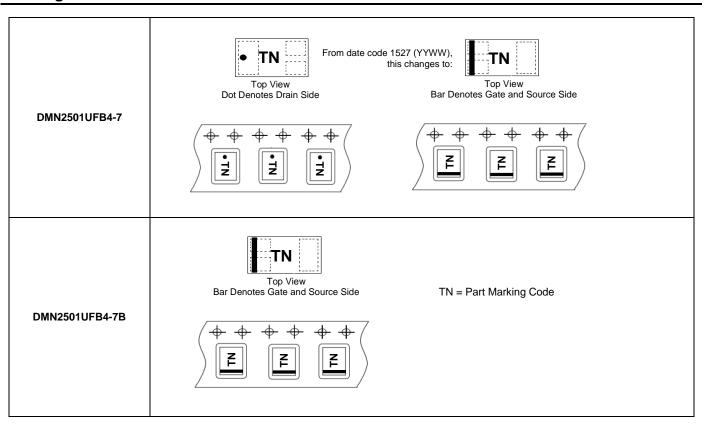
| Ī | Part Number | Case | Packaging |
|---|----------------|--------------|--------------------|
| | DMN2501UFB4-7 | X2-DFN1006-3 | 3,000/Tape & Reel |
| | DMN2501UFB4-7B | X2-DFN1006-3 | 10.000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.



Marking Information



| Characteristic | Symbol | Value | Units | | |
|--|------------------|--|------------------|------------|---|
| Drain-Source Voltage | V _{DSS} | 20 | V | | |
| Gate-Source Voltage | | | V _{GSS} | ±8 | V |
| Continuous Dusin Coursest (Nata 5) V | Steady State | T _A = 25°C T _A = 70°C | I _D | 1.0 0.8 | А |
| Continuous Drain Current (Note 5) V _{GS} = 4.5V | t<10s | $T_A = 25$ °C $T_A = 70$ °C | I _D | 1.2 0.9 | А |
| Continuous Durin Courset (Note C) V | Steady State | T _A = 25°C T _A = 70°C | I _D | 1.5 1.2 | А |
| Continuous Drain Current (Note 6) V _{GS} = 4.5V | t<10s | T _A = 25°C T _A = 70°C | I _D | 1.8 1.4 | А |
| Pulsed Drain Current (10µs pulse, duty cycle = 1%) | • | • | I _{DM} | 6 | А |
| Maximum Body Diode continuous Current | | | Is | 1 | Α |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | | | Units |
|----------------------|---|--|--|
| $T_A = +25^{\circ}C$ | ٥ | 0.5 | W |
| $T_A = +70^{\circ}C$ | PD | 0.3 | |
| Steady State | 5 | 251 | °C/W |
| t<10s | R_{θ} JA | 188 | |
| $T_A = +25^{\circ}C$ | 0 | 1.2 | W |
| $T_A = +70^{\circ}C$ | PD | 0.7 | |
| Steady State | 5 | 110 | °C/W |
| t<10s | R_{θ} JA | 82 | |
| | $T_{J_i}T_{STG}$ | -55 to +150 | °C |
| | $T_A = +70$ °C Steady State t<10s $T_A = +25$ °C $T_A = +70$ °C Steady State | $\begin{array}{c c} T_A = +70^{\circ}\text{C} & P_D \\ \hline \text{Steady State} & R_{\theta}\text{JA} \\ \hline t < 10\text{s} & R_{\theta}\text{JA} \\ \hline T_A = +25^{\circ}\text{C} & P_D \\ \hline T_A = +70^{\circ}\text{C} & \\ \hline \text{Steady State} & \\ \hline t < 10\text{s} & R_{\theta}\text{JA} \\ \hline \end{array}$ | $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$ |

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

^{6.} Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.



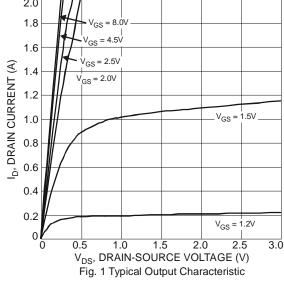
Electrical Characteristics (@ $T_A = \pm 25$ °C, unless otherwise specified.)

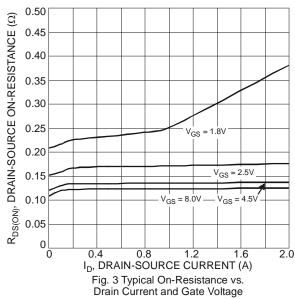
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|--|----------------------|-----|------|-----|-----------|---|--|
| OFF CHARACTERISTICS (Note 7) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 20 | - | - | V | $V_{GS} = 0V, I_D = 250\mu A$ | |
| Zero Gate Voltage Drain Current T _J = +25°C | I _{DSS} | - | - | 100 | nA | $V_{DS} = 20V, V_{GS} = 0V$ | |
| Gate-Source Leakage | I _{GSS} | - | - | ±1 | μΑ | $V_{GS} = \pm 6V$, $V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 7) | | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | 0.5 | 0.76 | 1.0 | V | $V_{DS} = V_{GS}$, $I_D = 250\mu A$ | |
| | | | 170 | 400 | | $V_{GS} = 4.5V, I_D = 600mA$ | |
| Static Drain-Source On-Resistance | R _{DS} (ON) | - | 200 | 500 | $m\Omega$ | $V_{GS} = 2.5V, I_D = 500mA$ | |
| | | | 260 | 700 | | $V_{GS} = 1.8V, I_D = 350mA$ | |
| Forward Transfer Admittance | Y _{fs} | - | 1.4 | - | S | V _{DS} = 10V, I _D = 400mA | |
| Diode Forward Voltage | V _{SD} | | 0.7 | 1.2 | V | $V_{GS} = 0V, I_{S} = 150mA$ | |
| DYNAMIC CHARACTERISTICS (Note 8) | • | | | | | • | |
| Input Capacitance | C _{iss} | - | 82 | - | pF | 101/11/ | |
| Output Capacitance | Coss | - | 12 | - | pF | $V_{DS} = 16V, V_{GS} = 0V,$ f = 1.0MHz | |
| Reverse Transfer Capacitance | C _{rss} | - | 10 | - | pF | | |
| Gate resistance | Rg | - | 83 | - | Ω | $V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$ | |
| Total Gate Charge (V _{GS} = 4.5V) | Qg | - | 1.1 | - | nC | | |
| Total Gate Charge (V _{GS} = 10V) | Qg | - | 2.0 | - | nC | 10\/ 1 250m A | |
| Gate-Source Charge | Qgs | - | 0.14 | - | nC | $V_{DS} = 10V, I_D = 250mA$ | |
| Gate-Drain Charge | Q _{qd} | - | 0.19 | - | nC | | |
| Turn-On Delay Time | t _{D(on)} | - | 6.6 | - | ns | | |
| Turn-On Rise Time | t _r | - | 6.4 | - | ns | $V_{DD} = 10V, V_{GS} = 4.5V,$ | |
| Turn-Off Delay Time | t _{D(off)} | - | 40.4 | - | ns | $R_{L} = 47\Omega, R_{G} = 10\Omega,$ $I_{D} = 200\text{mA}$ | |
| Turn-Off Fall Time | t _f | - | 17.3 | - | ns | | |

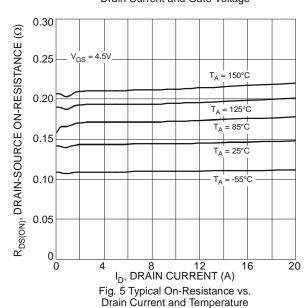
Notes:

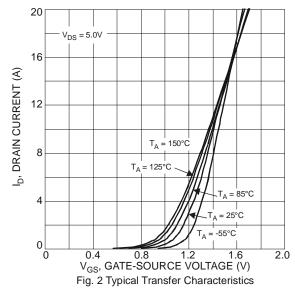
^{7.} Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.

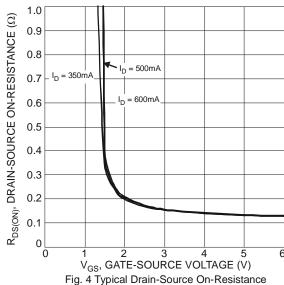












1.8

1.8

ON STANCE (NORMALIZED)

ON STANCE (NORMALIZE

vs. Gate-Source Voltage

Fig. 6 On-Resistance Variation with Temperature



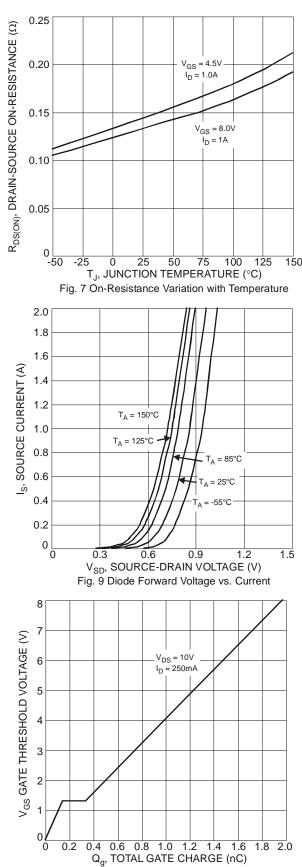


Fig. 11 Gate Charge

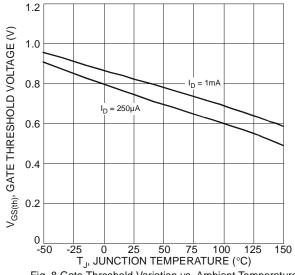
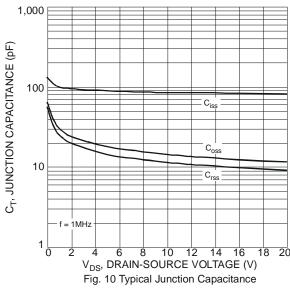
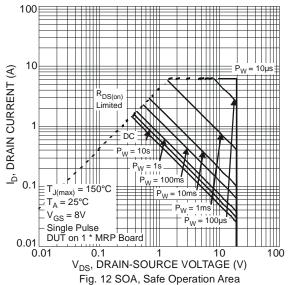
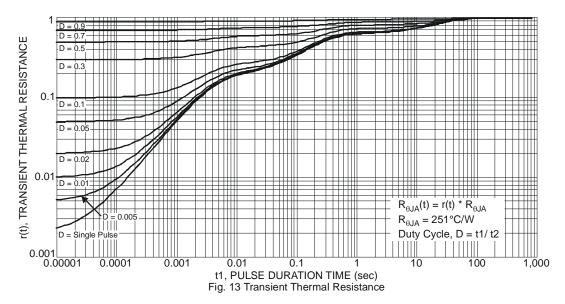


Fig. 8 Gate Threshold Variation vs. Ambient Temperature



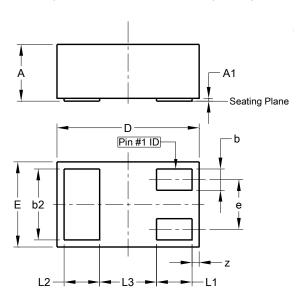






Package Outline Dimensions

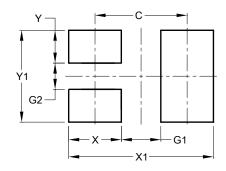
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



| X2-DFN1006-3 | | | | | |
|----------------------|------|------|------|--|--|
| Dim | Min | Max | Тур | | |
| Α | | 0.40 | _ | | |
| A1 | 0.00 | 0.05 | 0.03 | | |
| b | 0.10 | 0.20 | 0.15 | | |
| b2 | 0.45 | 0.55 | 0.50 | | |
| D | 0.95 | 1.05 | 1.00 | | |
| Е | 0.55 | 0.65 | 0.60 | | |
| e | 1 | 1 | 0.35 | | |
| L1 | 0.20 | 0.30 | 0.25 | | |
| L2 | 0.20 | 0.30 | 0.25 | | |
| L3 | 1 | 1 | 0.40 | | |
| Z | 0.02 | 0.08 | 0.05 | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) | | | |
|------------|---------------|--|--|--|
| С | 0.70 | | | |
| G1 | 0.30 | | | |
| G2 | 0.20 | | | |
| Х | 0.40 | | | |
| X1 | 1.10 | | | |
| Y | 0.25 | | | |
| Y1 | 0.70 | | | |



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